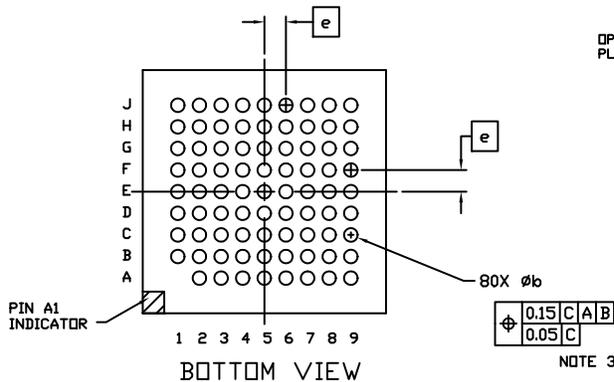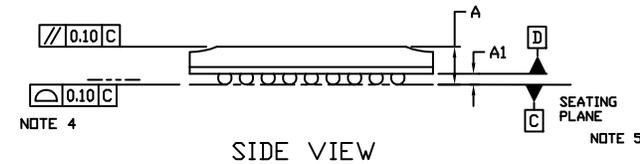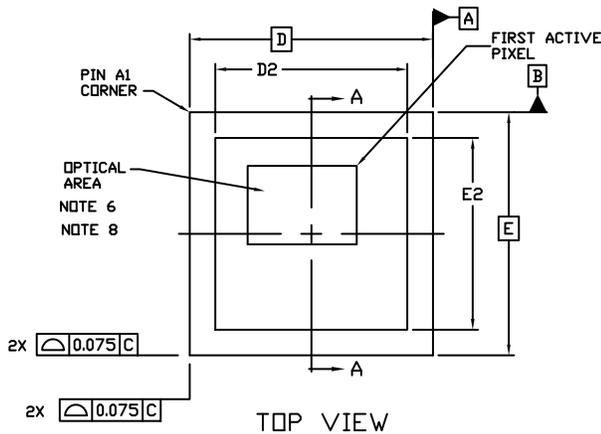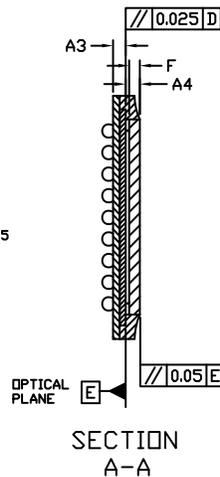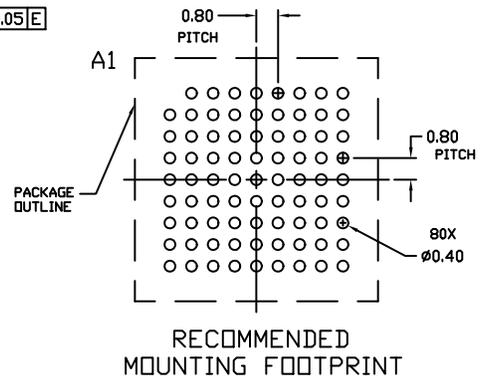**IBGA80 9x9**
CASE 503BM
ISSUE C

DATE 25 JUN 2018

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETERS

3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.

4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. MAXIMUM ROTATION OF THE OPTICAL AREA RELATIVE TO D AND E WILL BE 1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.

7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.

8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=−337.94 MICRONS, Y=1062.58 MICRONS ±75 MICRONS.

TOP VIEW

SIDE VIEW

BOTTOM VIEW

SECTION A-A

RECOMMENDED MOUNTING FOOTPRINT

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.55
A1	0.35	0.45
A3	0.425	0.525
A4	0.475	0.575
b	0.45	0.55
D	9.00 BSC	
D2	7.00	7.20
E	9.00 BSC	
E2	7.00	7.20
e	0.80 BSC	
F	0.38	0.42

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